

Single N-channel MOSFET

ELM32418LA-S

General description

ELM32418LA-S uses advanced trench technology to provide excellent $R_{ds(on)}$, low gate charge and low gate resistance.

Features

- $V_{ds}=40V$
- $I_d=20A$
- $R_{ds(on)} < 15m\Omega$ ($V_{gs}=10V$)
- $R_{ds(on)} < 27m\Omega$ ($V_{gs}=7V$)

Maximum absolute ratings

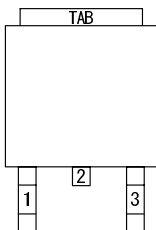
Parameter		Symbol	Limit	Unit	Note
Drain-source voltage		V_{ds}	40	V	
Gate-source voltage		V_{gs}	± 20	V	
Continuous drain current	$T_a=25^{\circ}C$	I_d	20	A	
	$T_a=100^{\circ}C$		16		
Pulsed drain current		I_{dm}	50	A	3
Power dissipation	$T_a=25^{\circ}C$	P_d	42	W	
	$T_a=100^{\circ}C$		32		
Junction and storage temperature range		T_j, T_{stg}	-55 to 150	$^{\circ}C$	

Thermal characteristics

Parameter		Symbol	Typ.	Max.	Unit	Note
Maximum junction-to-case	Steady-state	$R\theta_{jc}$		3	$^{\circ}C/W$	
Maximum junction-to-ambient	Steady-state	$R\theta_{ja}$		75	$^{\circ}C/W$	

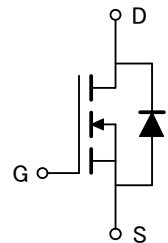
Pin configuration

TO-252-3 (TOP VIEW)



Pin No.	Pin name
1	GATE
2	DRAIN
3	SOURCE

Circuit



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Electrical characteristics

Ta=25°C

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit	Note
STATIC PARAMETERS							
Drain-source breakdown voltage	BVdss	Id=250 μ A, Vgs=0V	40			V	
Zero gate voltage drain current	Idss	Vds=32V, Vgs=0V			1	μ A	
		Vds=30V, Vgs=0V, Tj=125°C			10		
Gate-body leakage current	Igss	Vds=0V, Vgs= $\pm$ 20V			$\pm$ 250	nA	
Gate threshold voltage	Vgs(th)	Vds=Vgs, Id=250 μ A	1.2	2.0	3.0	V	
On state drain current	Id(on)	Vgs=10V, Vds=10V	50			A	1
Static drain-source on-resistance	Rds(on)	Vgs=10V, Id=20A		12.5	15.0	m Ω	1
		Vgs=7V, Id=10A		18.0	27.0	m Ω	
Forward transconductance	Gfs	Vds=10V, Id=20A		25		S	1
Diode forward voltage	Vsd	If=Is, Vgs=0V			1.3	V	1
Max. body-diode continuous current	Is				20	A	
Pulsed body-diode current	Ism				50	A	3
DYNAMIC PARAMETERS							
Input capacitance	Ciss	Vgs=0V, Vds=10V, f=1MHz		1145	1450	pF	
Output capacitance	Coss			255	355	pF	
Reverse transfer capacitance	Crss			95	145	pF	
SWITCHING PARAMETERS							
Total gate charge	Qg	Vgs=10V, Vds=20V, Id=10A		23.0		nC	2
Gate-source charge	Qgs			3.6		nC	2
Gate-drain charge	Qgd			3.0		nC	2
Turn-on delay time	td(on)	Vgs=10V, Vds=20V, Id $\approx$ 1A RI=1 Ω , Rgen=6 Ω		3.2	6.4	ns	2
Turn-on rise time	tr			10.8	21.7	ns	2
Turn-off delay time	td(off)			17.1	30.8	ns	2
Turn-off fall time	tf			5.3	10.7	ns	2
Body diode reverse recovery time	trr	If=20A, dI/dt=100A/ μ s		60		ns	
Body diode reverse recovery charge	Qrr	If=20A, dI/dt=100A/ μ s		43		nC	

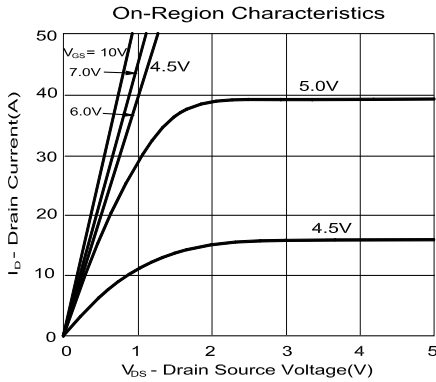
NOTE :

1. Pulse test : Pulsed width $\leq 300\mu$ sec and Duty cycle $\leq 2\%$.
2. Independent of operating temperature.
3. Pulsed width limited by maximum junction temperature.

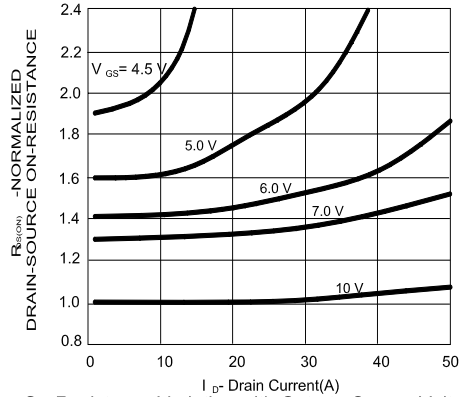
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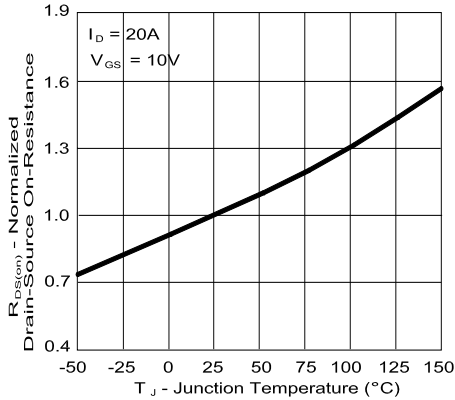
Typical electrical and thermal characteristics



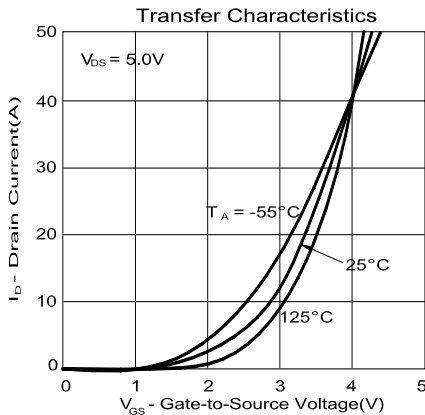
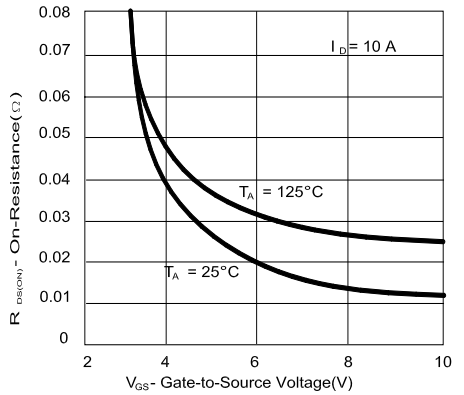
On-Resistance Variation with Drain Current and Gate Voltage



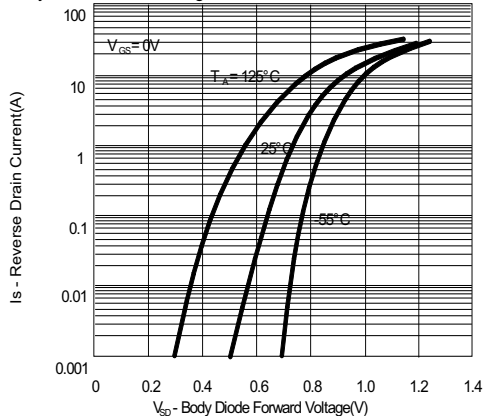
On-Resistance Variation with Temperature



On-Resistance Variation with Gate-to-Source Voltage



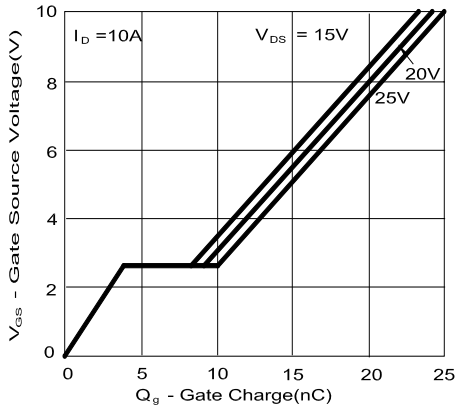
Body Diode Forward Voltage Variation with Source Current and Temperature



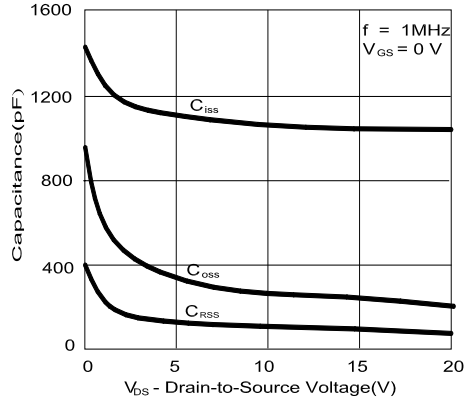
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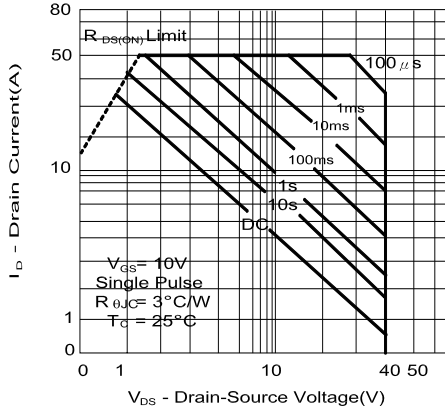
Gate Charge Characteristics



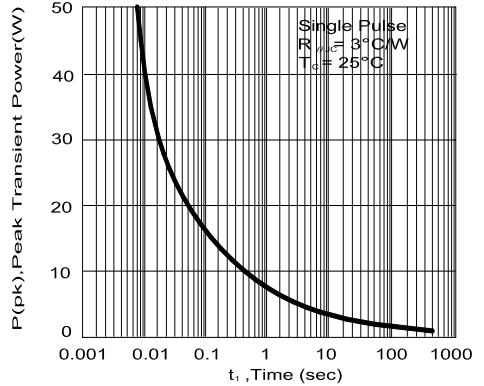
Capacitance Characteristics



Maximum Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve

